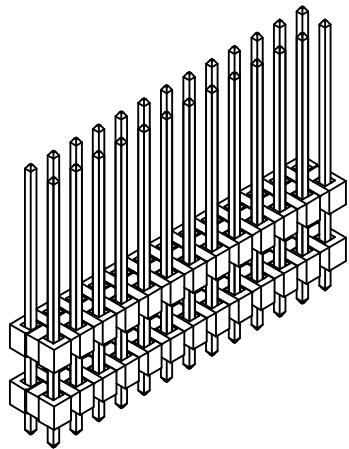
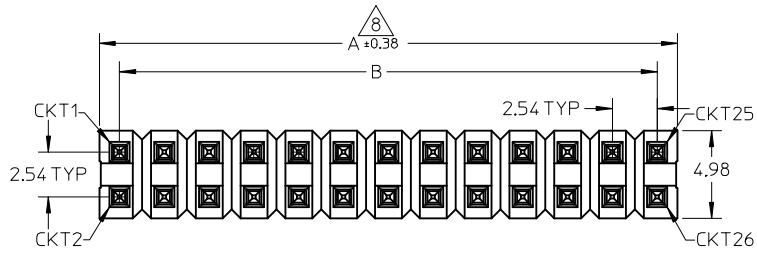
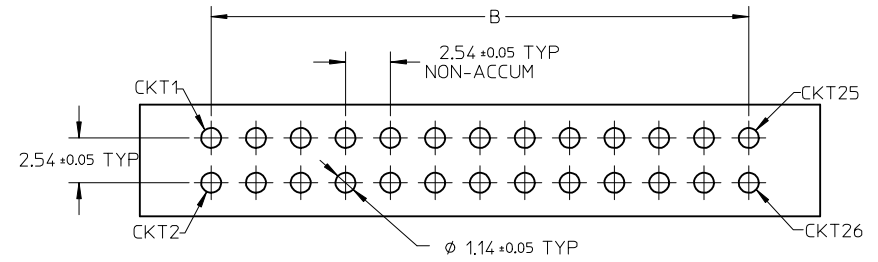
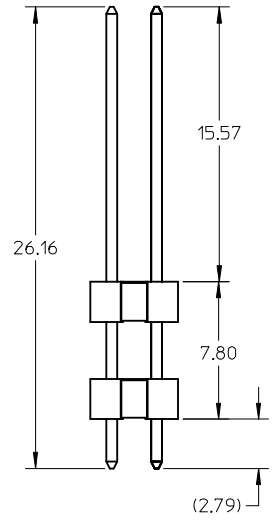
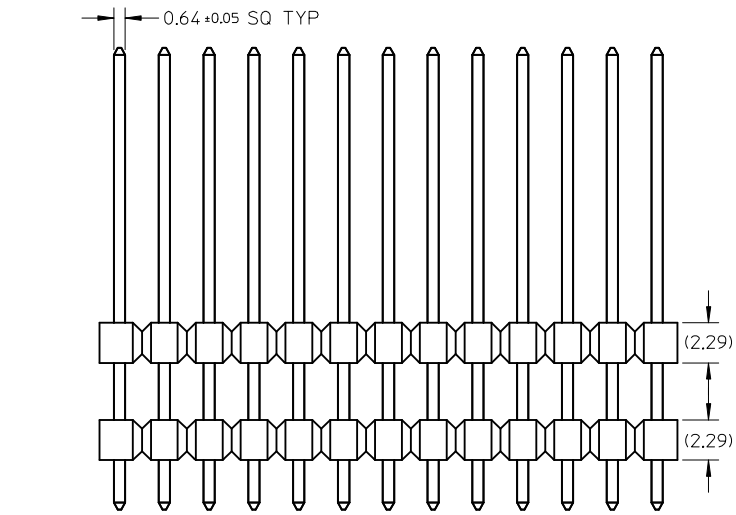


PART NO FOR TRAY PACKAGING	CKT SIZE	P E G	VOID PIN POSITION	DIMENSION	
				A	B
87797-0026	26	N	-----	33.02	30.48



NOTES

- MATERIAL:
HSG: LCP, GLASS-FILLED, UL94V-0,
COLOR, BLACK
PIN: COPPER ALLOY 0.64 mm SQ.
- PLATING TYPE:
0.254µm/10µm MIN GOLD IN CONTACT AREA OVER
1.900µm/75µm MIN TIN SELECTIVE IN SOLDER AREA BOTH OVER
1.270µm/50µm NICKEL OVERALL
- PARTS TO BE PACKED IN TRAY
- PCB THICKNESS 1.6+/-0.10mm
- PRODUCT SPECIFICATION: PS-87920-019
- WAFER TO BE FLAT WITHIN 0.003 mm/mm
- PART IS NOT STACKABLE ON 2.54 CENTER
- IRREGULAR CIRCUIT CUTOFF WITHIN BREAKAWAY SECTION IS PERMISSIBLE. CUTTING OR CHIPPING OF THE MAIN BODY IS NOT ACCEPTABLE



EC NO: S2006-1078 DRWN:SKL IM01 CHKD:CWLAM APPR:PATEY 2006/05/03	QUALITY SYMBOLS ▽=0 Ⓒ=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	SKL IM01	2006/04/20	CUSTOM HEADER 2.54MM PITCH DUAL ROW HEADER, THRU HOLE, 26CKT			
		3 PLACES	± ---	± ---	CHECKED BY	DATE				
2 PLACES	± 0.2	± ---	CWLAM	2006/04/28	MOLEX INCORPORATED					
1 PLACE	± ---	± ---	APPROVED BY	DATE						
	ANGULAR ± 3 °		PATEY	2006/04/28	MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-87797-178		1 OF 1			
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									